



- 1 Substrate: 3.18mm ± 0.25 mm [0.125" ± 0.001 "] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. Au plating. (RoHS)
- 2 Solder ball: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

Description: BGA Surface Mount Adaptor
 336 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters ± 0.03 mm [± 0.001 "], PCB perimeters ± 0.13 mm [± 0.005 "], PCB thicknesses ± 0.18 mm [± 0.007 "], pitches (from true position) ± 0.08 mm [± 0.003 "], all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA336B-B-05F Drawing	Status: Released	Scale: 3:1	Rev: A
 © 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: S.Natarajan		Date: 5/15/06
	File: SF-BGA336B-B-05F Dwg		Modified: